

Specifications

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|------------------------------|---|---|
| Video | GPU Feature Support | Intel® HD Graphics 500 (9th Gen Intel® Core™ i3) |
| | Digital Display Interface | DP, HDMI |
| | LVDS | 1x LVDS |
| | USB | 1x USB 3.0 |
| Audio | Chipset | Integrated on SoC |
| | Codec | On carrier Express-BASE6 (ALC886 standard support) |
| Ethernet | Intel® MAC/PHY Interface | Intel® Ethernet Connection I225 series (I225-IT 9 supports TSN by build option) 2.5GbE and 1000/100/10 Mbit/s Ethernet connection GbE0_SDP if TSN support enabled (TBC) |
| Multi I/O and Storage | USB | 4x USB 3.0 2x SATA 6Gb/s (SATA 0-1) |
| | HDMI | HDMI |
| | (PEHGGHG)HDWXUHV | (1x, 0x)DFNXS%, 26HEXJ7\$ |
| Super I/O | Supported on carrier if needed (standard support W83627DHG-P, other Super I/O supported by project basis) | |
| TPM | Chipset | Infineon |
| | Type | TPM 2.0 (SPI based) |
| Power | Standard Input Management | ATX: V±5% / 5Vsb ±5%; or AT: V±5% |
| | Power States | ACPI 5.0 compliant, Smart Battery support (TBC) |
| | ECO Mode | C1-C6, S0, S1, S3, S4, S5, S5 ECO mode (Wake on USB S3/S4, WOL S3/S4/S5) (TBC) |
| | ECO Mode | Supports deep S5 mode for power saving |
| Mechanical and Environmental | Form Factor | PICMG COM.0: Rev 3.1 Type 6 |
| | Dimension | RPSDFW size: 86 mm x 95 mm |
| | Operating Temperature | Standard: 0°C to 60°C Extreme Rugged: -40°C to 85°C (VWDGDUGG99SXWBO) |
| | +XPLGLW | 5-90% RH operating, non-condensing 5-95% RH storage (and operating with conformal coating) |
| | 6KRFNDG9LEUDWLRO | IEC 60068-2-64 and IEC-60068-2-27 MIL-STD-202F, Method 213B, Table 213-I, Condition A and Method 214A, Table 214-I, Condition D (TBC) |
| | +57 | Thermal Stress, Vibration Stress, Thermal Shock and Combined Test |
| Operating Systems | Standard Support | Windows 10 IoT LTSC, Ubuntu 17.04 (HUIHO) Yocto 1.7.6 (HUIHO) |

1RWHp%XLOGRSWLROqLQLFDWHVDOOWHUWLYH%20FRDUXDWLROVRVXSSRUWDGGLWLRORUDOWHUWLYHIXEWLRQWKDWDUHWWDYDLODEOHRWVKHVWDGUGSURGXFW
%HDDUHWKDWKHWVPEXLOGRSWLROPEHUUVZOOBHGWRHEDZFUHDWHDGDKLVZOOUHVXOWLSURGXFWLROHDGWLPHV

Ordering Information

Module

| | |
|-------------------------|--|
| cExpress-ALN-x7425E-16G | Compact size COM Express Type 6 with Intel Alder Lake-N Atom x7425E(4C), 16GB LPDDR5 |
| cExpress-ALN-x7213E-4G | Compact size COM Express Type 6 with Intel Alder Lake-N Atom x7213E(2C), 4GB LPDDR5 |
| cExpress-ALN-x7211E-8G | Compact size COM Express Type 6 with Intel Alder Lake-N Atom x7211E(4C), 8GB LPDDR5 |
| cExpress-ALN-i3-N305-8G | Compact size COM Express Type 6 with Intel Alder Lake-N i3-N305(8C), 8GB LPDDR5 |
| cExpress-ALN-N200-8G | Compact size COM Express Type 6 with Intel Alder Lake-N N200 Processor(4C), 8GB LPDDR5 |

Note: For certain processor or memory capacity SKUs not listed, please contact our ADLINK representative.

Accessories

Heat Spreaders

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|--------------|--|
| HTS-cEL-B -I | Heatspreader for cExpress-ALN with threaded standoffs for bottom mounting |
| HTS-cEL-BT-I | Heatspreader for cExpress-ALN with through-hole standoffs for top mounting |

Passive Heatsinks

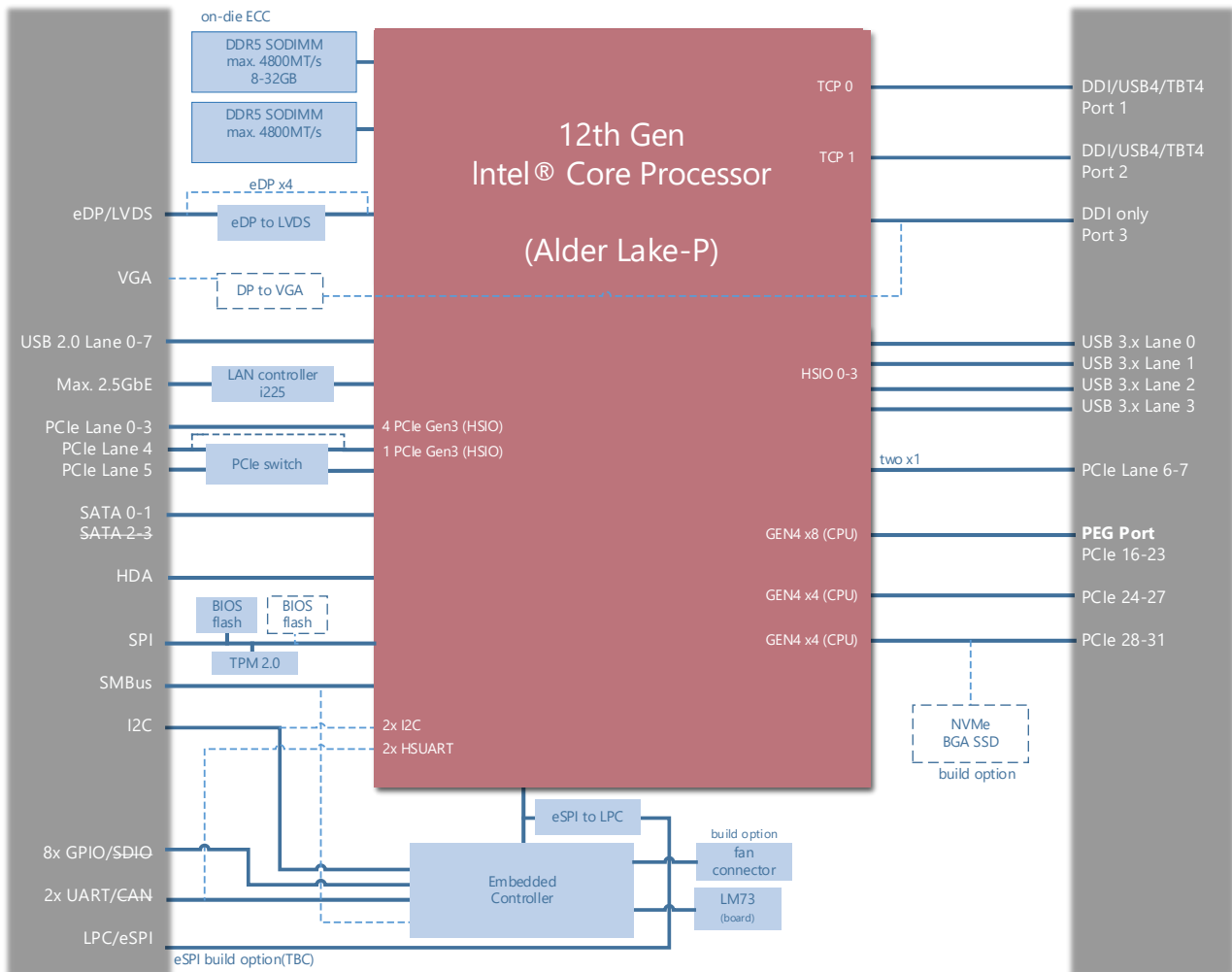
| | |
|--------------|--|
| THS-cEL-B-I | Low-profile Heatsink for cExpress-ALN with threaded standoffs for bottom mounting |
| THS-cEL-BT-I | Low-profile Heatsink for cExpress-ALN with through-hole standoffs for top mounting |
| THSH-cEL-B-I | High-profile Heatsink for cExpress-ALN with threaded standoffs for bottom mounting |

Active Heatsinks

| | |
|------------|---|
| THSF-cEL-B | High-profile Heatsink with Fan for cExpress-ALN with threaded standoffs for bottom mounting |
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Note: "Build option" indicates an alternative BOM configuration to support additional or alternative functions that are not available on the standard product. Be aware that these "build option" part numbers will need to be newly created and this will result in production lead times.

Block diagram



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